



Donald L. Wood
**Professional Conference Travel Grants
for Engineering Undergraduates**

APPLICATION OVERVIEW

A limited number of travel grants of \$150 (maximum) are available from the School of Engineering and Applied Sciences' Deans Office for undergraduate engineering students who are in good academic standing and who wish to travel to professional engineering conferences. It is hoped that participation in professional conferences will increase your interest and confidence in engineering, as well as expose you to networking opportunities in your field of study.

Qualifications: Engineering students in good academic standing (ie: not on academic probation) who are paid members of an engineering professional society may apply. Proof of membership must accompany application. Priority will be given to students presenting papers or workshops at the conference.

Matching Funds: Applications from students who seek matching funds from other sources will be given higher priority. The matching fund sponsor must approve the proposal and be willing to cover at least an amount equal to the travel grant from the Deans Office.

Application: Each applicant needs to prepare a short description of the benefits of participation in the particular conference along with a budget request. Style is important; we would like to have an attractive 1-2 page statement including a picture of yourself and a short biography. Applications must be approved by your matching fund sponsor (if applicable) and delivered to Lisa Norwood at the School of Engineering and Applied Sciences Deans Office in Lattimore 306.

Final Report: Upon return from the conference, you are expected to turn in a similar short report about your conference participation experience, along with your original expense receipts.

Deadlines: Requests for funding should be submitted as far in advance of the conference as possible, allowing 4-6 weeks for a decision to be made and funding to be dispersed. All requests for funding should be submitted no later than April 15 of each academic year. It is possible to apply for funding reimbursement after a conference, provided that original receipts are submitted with the application. The final report should be submitted within a month of the end of the conference. All receipts for reimbursement must be submitted no later than April 1.

Funding: These travel grants are made possible by a generous donation from the estate of Donald L. Wood. The student application and final report will be used to describe our accomplishments to the family of this sponsor.

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Application

Personal Information

Last Name Middle Name First Name Student ID Number

School Address City State ZIP Code

Phone Major Class Year GPA

What engineering professional societies are you a **paid** member of?

<u>Society Name</u>	<u>Membership ID</u>
_____	_____
_____	_____
_____	_____

Conference Information

Conference Name Conference dates

<input type="checkbox"/> Yes <input type="checkbox"/> No	_____	<input type="checkbox"/> Yes <input type="checkbox"/> No	_____
Have you ever attended this conference before?	If yes, give date.	Will you be presenting a paper or a workshop at this conference?	If yes, please list the title of your paper or workshop.

Write a short description of what you perceive the benefits of participating in this conference will be.

Budget and Funding Information

Please provide an estimate of the costs for attending this conference. Include such things as conference registration, transportation, lodging and meals. If the conference has already occurred, please attach original receipts for all expenses.

<u>Expense</u>	<u>Amount</u>
_____	_____
_____	_____
_____	_____
_____	_____
_____	_____
_____	_____
_____	_____
_____	_____
TOTAL	_____

How much funding are you requesting through the *Donald L. Wood Travel Grants for Engineering Undergraduates*? _____

Will you be receiving funding from other sources? Yes No

<u>Source</u>	<u>Amount</u>
_____	_____
_____	_____
_____	_____

Attachments

Please remember to attach the following items to this application:

- Picture of yourself
- Personal statement or resume
- Original receipts if this conference has already occurred at the time of application

Release Statement

I certify that, to the best of my knowledge, all of the information provided in this application is accurate. I understand that if I am selected to receive a *Donald L. Wood Travel Grant for Engineering Undergraduates*, I will be expected to provide a final report on my conference participation experience along with my original expense receipts. I am aware that my picture and some information from this application, my attached resume and/or my final report may be shared with the family of Donald L. Wood.

Signature of Applicant

Date